

WEBENCH® Assembly Document

VinMin = 12.0V VinMax = 14.0V Vout = 5.0V Iout = 2.0A Device = LMZ12001TZ-ADJ/NOPB Topology = Buck Created = 6/6/15 2:20:20 AM BOM Cost = \$5.56 Total Pd = 0.72W Footprint = 278.0 mm<sup>2</sup> BOM Count = 10

Design: 1684581/3 LMZ12001TZ-ADJ/NOPB LMZ12001TZ-ADJ/NOPB 12.0V-14.0V to 5.00V @ 2.0A

## **General Description**

The LMZ12003 Build It Board is designed to provide a flexible, tested Printed Circuit Board (PCB) platform for customers to quickly assemble and evaluate LMZ12003 custom power supply solutions. The board is a four-layer surface mount layout using 1oz copper. The board can accommodate a wide range of input and output capacitors. Majority of the components are mounted on the top-side layer and few are mounted on the bottom-side layer.

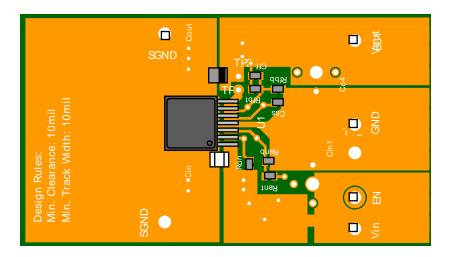


FIGURE 1 - Board Top Side Assembly Diagram

### **BuildIt BOM**

#	Component Name(s)	Part Number	Manufacture	Qty	Unit Price	Top View
1.	Cout	6TPE120MAZB	Panasonic	1	\$1.57	3528-21 0.0
2.	Rent	ERJ-6ENF3402V	Panasonic	1	\$0.1	0805 0.0
3.	Rfbt	ERJ-6ENF5621V	Panasonic	1	\$0.1	0805 0.0
4.	Rfbb	ERJ-6ENF1071V	Panasonic	1	\$0.1	0805 0.0
5.	Css	GRM216R71H103KA01D	MuRata	1	\$0.1	0805 0.0
6.	Cin	GRM32ER61E226KE15L	MuRata	1	\$0.67	1210 0.0
7.	PC Board	551600437-001	Texas Instruments	1	\$10.2	0.0
8.	Renb	ERJ-6ENF3741V	Panasonic	1	\$0.1	0805 0.0

#	Component Name(s)	Part Number	Manufacture	Qty	Unit Price	Top View
9.	U1	LMZ12001TZ-ADJ/NOPB	Texas Instruments	1	\$11.0	TZA07A 0.0
10.	J1,J2,J3,J4	1502-2	Keystone	4	\$0.33	0.0
11.	Ron	ERJ-6ENF9092V	Panasonic	1	\$0.1	0805 0.0
12.	Cf	CC0805KRX7R9BB223	Yageo America	1	\$0.1	0805 0.0
VinMin = VinMax		E	Cr C	)ldut > Rfb	Cout 120.0 µF 36.0 mOhm Reseries	Vout = 5.0V lout = 2.0A

# Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

#### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage (12.0 V) and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter to Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply but the voltage remains near zero there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

#### Load Testing

The test setup for load testing is shown in FIGURE 3. The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated outptut power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. The four basic test conditions are listed in figure 4. In all cases, Vout should be well controlled within the targeted voltage range of 4.5 Volts to 5.5 Volts: When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit. The following figure depicts a method of wrapping voltage probes with uninsulated wire to achieve accurate measurements:

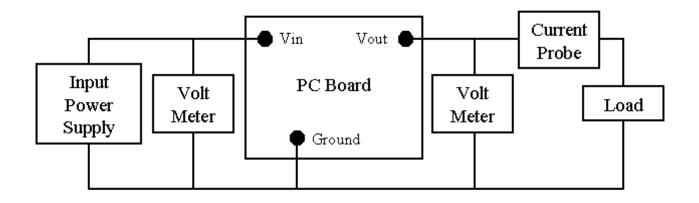


FIGURE 3 - Test setup for load testing

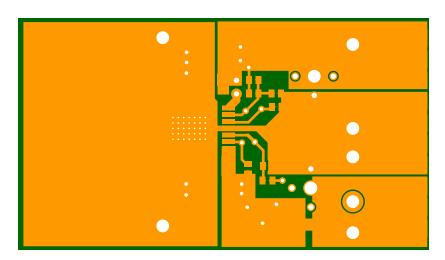


FIGURE 5 - Top Side Copper

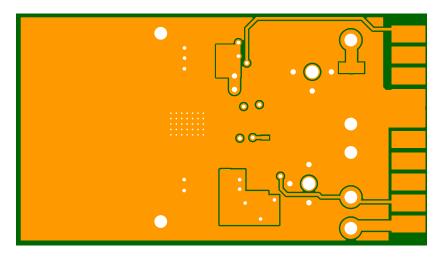


FIGURE 6 - Bottom Side Copper

# **Design Inputs**

	#	Name	Value	Description
_	1.	lout	2.0 A	Maximum Output Current
	2.	lout1	2.0 Amps	Output Current #1
	3.	VinMax	14.0 V	Maximum input voltage
	4.	VinMin	12.0 V	Minimum input voltage

#	Name	Value	Description
5.	Vout	5.0 V	Output Voltage
6.	Vout1	5.0 Volt	Output Voltage #1
7.	base_pn	LMZ12003	Texas Instruments Base Part Number
8.	source	DC	Input Source Type
9.	ta	50.0 degC	Ambient temperature

# **Design Assistance**

1. LMZ12003 Product Folder: http://www.ti.com/product/LMZ12003: contains the data sheet and other resources.

Texas Instruments' WEBENCH simulation tools attempt to recreate the performance of a substantially equivalent physical implementation of the design. Simulations are created using Texas Instruments' published specifications as well as the published specifications of other device manufacturers. While Texas Instruments does update this information periodically, this information may not be current at the time the simulation is built. Texas Instruments does not warrant the accuracy or completeness of the specifications or any information contained therein. Texas Instruments does not warrant that any designs or recommended parts will meet the specifications you entered, will be suitable for your application or fit for any particular purpose, or will operate as shown in the simulation in a physical implementation. Texas Instruments does not warrant that the designs are production worthy.

You should completely validate and test your design implementation to confirm the system functionality for your application prior to production.

Use of Texas Instruments' WEBENCH simulation tools is subject to Texas Instruments' Site Terms and Conditions of Use. Prototype boards based on WEBENCH created designs are provided AS IS without warranty of any kind for evaluation and testing purposes and are subject to the terms of the Evaluation License Agreement.